CRMVTL0413A

N-Channel 40V, $10.9m\Omega$ Typ. Power MOSFET

Description

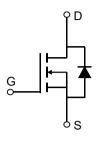
Features

• 40V, 13A

$$R_{DS(ON)}$$
 Typ = 10.9m Ω @ V_{GS} = 10V

$$R_{DS(ON)}$$
 Typ = 13.5m Ω @ V_{GS} = 4.5V

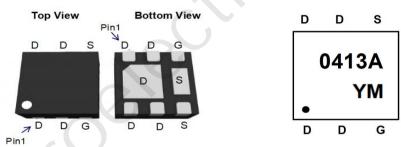
- Advanced Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- Lead Free





Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMVTL0413A	0413A	DFN2020-6L	TAPING	7"	3000	120000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		40	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _C = 25°C	13	Α
I _D	Continuous Diain Current	T _C = 100°C	7.8	А
I _{DM}	Pulsed Drain Current (1)		52	Α
P_{D}	Power Dissipation	T _C = 25°C	5	W
$R_{ hetaJC}$	Thermal Resistance, Junction to Case		25	°C/W
T_J,T_STG	Junction & Storage Temperature Range		-55 to 150	°C

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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 40V, V_{GS} = 0V$	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				<u>C</u>	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	1.3	1.8	V
В	Chatia Dania Comma ON Daniatana (2)	$V_{GS} = 10V, I_D = 5A$	-	10.9	14.2	mΩ
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽²⁾	$V_{GS} = 4.5V, I_D = 3A$	-	13.5	17.6	mΩ
) Dynamic	Characteristics					
C_{iss}	Input Capacitance			1172	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 20V,$ f = 1MHz	X -	104	-	pF
C_{rss}	Reverse Transfer Capacitance	1 - 1101112		84	-	pF
Q_g	Total Gate Charge		9 -	26	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 20V, I_{D} = 5A$	-	6	-	nC
Q_gd	Gate Drain("Miller") Charge	V _{DS} - 20V, I _D - 0A	-	5	-	nC
Switchin	g Characteristics					
$t_{d(on)}$	Turn-On DelayTime	.r ()	-	7	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 20V$	-	11	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	$I_D = 5A$, $R_{GEN} = 3\Omega$	-	26	-	ns
t_f	Turn-Off Fall Time		-	5	-	ns
Orain-So	urce Diode Characteristics and M	Max Ratings				
I _S	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	13	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	52	Α
V _{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 5A$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I - 50 dildt - 1000/:	-	10	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 5A$, di/dt = 100A/us	-	6	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} Pulse Test: Pulse Width $\!\!\!\!<\!300\mu s,$ Duty Cycle $\!\!\!<\!0.5\%.$

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Test Circuit

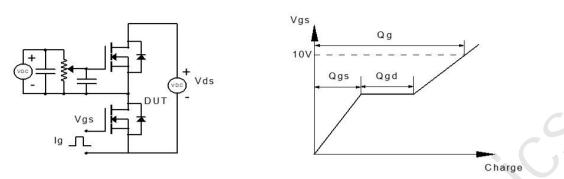


Figure 1: Gate Charge Test Circuit & Waveform

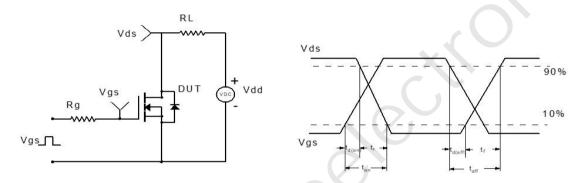


Figure 2: Resistive Switching Test Circuit & Waveform

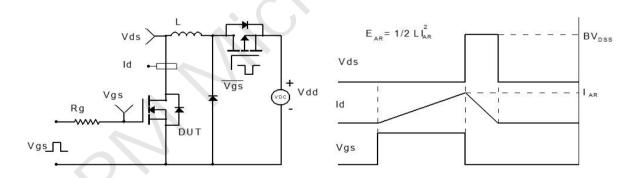


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

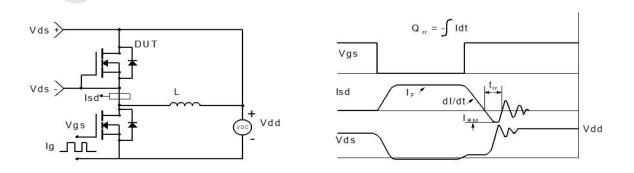


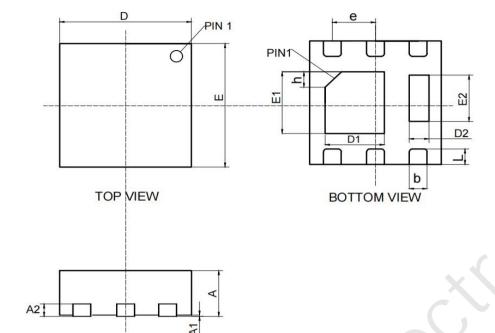
Figure 4: Diode Recovery Test Circuit & Waveform

SIDE VIEW

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Package Mechanical Data(DFN2020-6L)



SYMBOL	MIN	NOM	MAX
Α	0.70	0.75	0.80
A1	NA	0.02	0.05
A2	0.18	0.20	0.25
b	0.20	0.27	0.34
D	1.95	2.00	2.05
E	1.95	2.00	2.05
D1	0.80	0.90	1.00
E1	0.90	1.00	1.10
D2	0.20	0.30	0.40
E2	0.65	0.75	0.85
L	0.20	0.25	0.35
h	0.20	0.25	0.30
е	0.65 BSC		

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